CORFIL® 658

Epoxy; Epoxide

Cytec Industries Inc.

Message:

CORFIL 658 is a one-part epoxy material designed for use in insert or edge filling of honeycomb structure. The low viscosity of CORFIL 658 makes it especially suitable for automated or hand filling of small cell sized honeycomb. The thixotropic nature of CORFIL 658 ensures that there is no slump or resin separation during cure. CORFIL 658 is shipped frozen in sealed metal pails or plastic tubes packed with dry ice or by refrigerated carrier.
FEATURES & BENEFITS
Excellent spreadability and extrudability
Compatible with most 350°F (177°C) curing epoxy prepregs
Good compressive strength
SUGGESTED APPLICATIONS
Filling of honeycomb core in sandwich structures, especially in co-bond or co-cure applications

General Information	
Features	Good Compressive Strength Thixotropic
Uses	Adhesives Filling Applications Structural Parts
Appearance	White
Forms	Paste
Processing Method	Extrusion Potting

Physical	Nominal Value	Unit
Specific Gravity	0.650 to 0.750	g/cm³
Mechanical	**Nominal Value**	**Unit**
Compressive Strength (24°C)	44.8	MPa
Additional Information	**Nominal Value**	**Unit**
Volatiles	< 1.0	%

WECHAT